



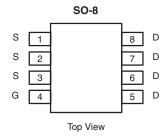
N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^a	Q _g (Typ.)		
30	0.0042 at V _{GS} = 10 V	28	29 nC		
30	$0.0057 \text{ at V}_{GS} = 4.5 \text{ V}$	24	29110		

FEATURES

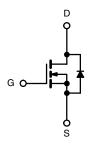
- Halogen-free According to IEC 61249-2-21 Available
- TrenchFET[®] Power MOSFETs
- 100 % R_g Tested





Ordering Information: Si4842BDY-T1-E3 (Lead (Pb)-free)

Si4842BDY-T1-GE3 (Lead (Pb)-free and Halogen-free)



N-Channel MOSFET

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	30	V	
Gate-Source Voltage		± 20	V	
	T _C = 25 °C		28	
Continuous Drain Current (T _J = 150 °C)	T _C = 70 °C	1 1	23	
Continuous Diain Current (1) = 130 °C)	T _A = 25 °C	l I _D	20 ^{b, c}	
	T _A = 70 °C	1 1	16 ^{b, c}	Α
Pulsed Drain Current		I _{DM}	60	
Continuous Source-Drain Diode Current	T _C = 25 °C		5.6	
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	2.7 ^{b, c}	
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	35	
Avalanche Energy	L=0.1 IIII	E _{AS}	61	mJ
	T _C = 25 °C		6.25	
Maximum Dawar Dissination	T _C = 70 °C	P _D	4.0	W
Maximum Power Dissipation	T _A = 25 °C	1 '0 [3.0 ^{b, c}	VV
	T _A = 70 °C	1	1.9 ^{b, c}	
Operating Junction and Storage Temperature	T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS								
Parameter	Symbol	Typical	Maximum	Unit				
Maximum Junction-to-Ambient ^{b, d}	t ≤ 10 s	R _{thJA}	32	42	°C/W			
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	15	20]			

Notes:

- a. Based on T_C = 25 °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 10 s.
- d. Maximum under Steady State conditions is 90 $^{\circ}\text{C/W}.$

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 1 mA	30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 050 ·· A		30		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_{J}$	$I_{D} = 250 \mu A$		- 6.4			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	1.4		3	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
7 0 1 1/1 5 1 0 1	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V			1		
Zero Gate Voltage Drain Current		V_{DS} = 30 V, V_{GS} = 0 V, T_{J} = 55 °C			10	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	30			A	
		$V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$		0.0034	0.0042	_	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 15 \text{ A}$		0.0047	0.0057	Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 20 A		90		S	
Dynamic ^b				l			
Input Capacitance	C _{iss}			3650		pF	
Output Capacitance	C _{oss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		635			
Reverse Transfer Capacitance	C _{rss}			300			
Total Gate Charge		$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 25 \text{ A}$		68	100		
				29	43		
Gate-Source Charge	Q _{gs}			12.6		nC	
Gate-Drain Charge	Q _{gd}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 25 \text{ A}$		9.4			
Gate Resistance	R _g	f = 1 MHz		1.25	2	Ω	
Turn-on Delay Time	t _{d(on)}			125	190		
Rise Time	t _r	V 45VD 450		190	280	-	
Turn-Off Delay Time	t _{d(off)}	$V_{DD} = 15 \text{ V}, R_L = 1.5 \Omega$ $I_D \cong 10 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_q = 1 \Omega$		38	60		
Fall Time	t _f	1D = 10 A, VGEN = 4.5 V, Hg = 1.52		13	20		
Turn-on Delay Time	t _{d(on)}			15	25		
Rise Time	t _r	V 15VD 150		15	25	ns	
Turn-Off Delay Time	t _{d(off)}	V_{DD} = 15 V, R_L = 1.5 Ω $I_D \cong$ 10 A, V_{GEN} = 10 V, R_α = 1 Ω		42	65		
Fall Time	t _f	1D = 10 A, VGEN = 10 V, Hg = 132		8	15		
Drain-Source Body Diode Characteristi	cs		L		•		
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			5.6	۸	
Pulse Diode Forward Current ^a	I _{SM}				60	Α	
Body Diode Voltage	V _{SD}	I _S = 2.7 A		0.74	1.1	٧	
Body Diode Reverse Recovery Time	t _{rr}			34	55	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	1 40 A 41/44 400 A/ T 05 00		31	50	nC	
Reverse Recovery Fall Time	t _a	$I_F = 10 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		18		ns	
Reverse Recovery Rise Time	t _b			16			

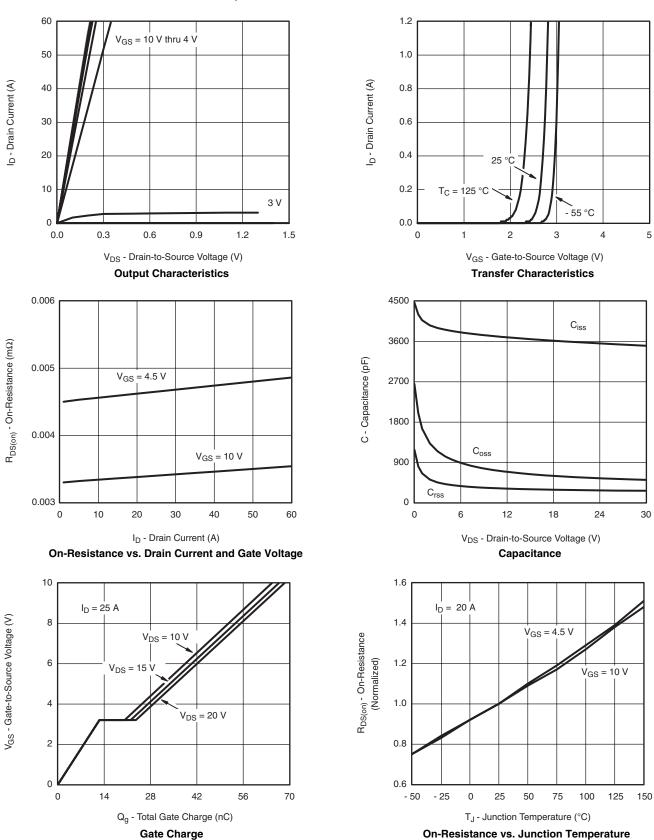
- a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



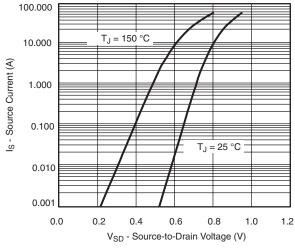


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

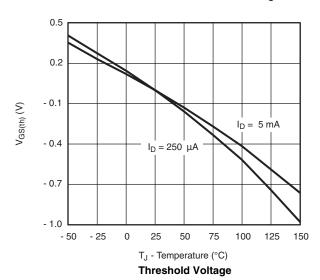


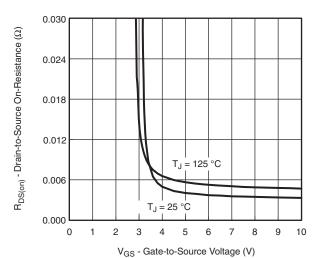
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

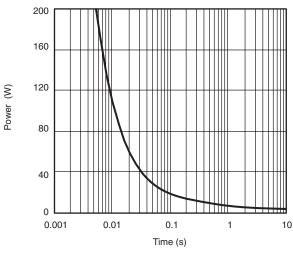




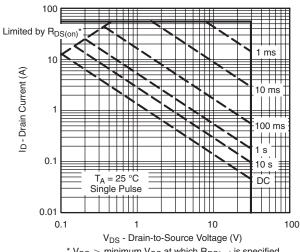




On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient

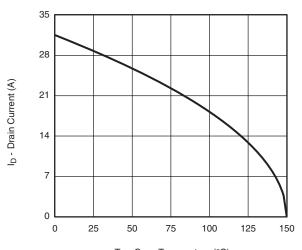


* $V_{GS} > minimum \ V_{GS}$ at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient

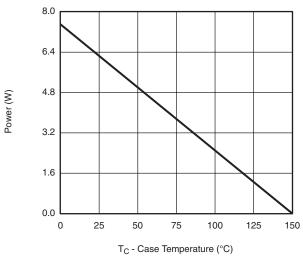


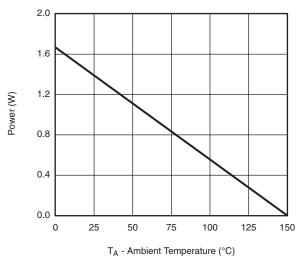
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 $T_{\mbox{\scriptsize C}}$ - Case Temperature (°C)

Current Derating*





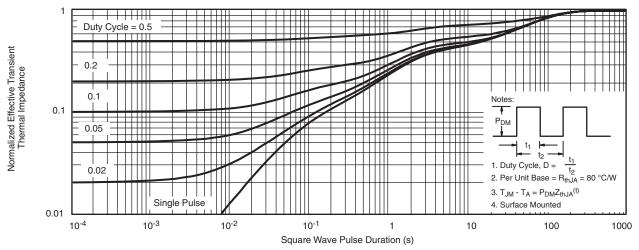
Power, Junction-to-Foot Power, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

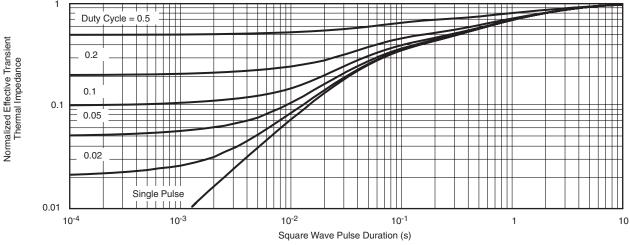
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







	MILLIM	IETERS	INCHES			
DIM	Min	Max	Min	Max		
Α	1.35	1.75	0.053	0.069		
A ₁	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
Е	3.80	4.00	0.150	0.157		
е	1.27	BSC	0.050	0.050 BSC		
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
ECN: C-06527-Rev. I. 11-Sep-06						

DWG: 5498

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RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

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